

NDC7002N

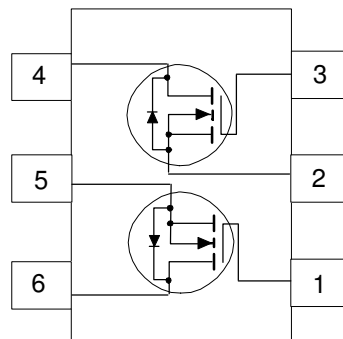
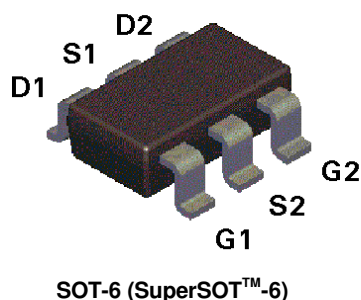
Dual N-Channel Enhancement Mode Field Effect Transistor

General Description

These dual N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process has been designed to minimize on-state resistance, provide rugged and reliable performance and fast switching. These devices is particularly suited for low voltage applications requiring a low current high side switch.

Features

- 0.51A, 50V, $R_{DS(ON)} = 2\Omega @ V_{GS}=10V$
- High density cell design for low $R_{DS(ON)}$
- Proprietary SuperSOT™-6 package design using copper lead frame for superior thermal and electrical capabilities.
- High saturation current.



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	NDC7002N	Units
V_{DSS}	Drain-Source Voltage	50	V
V_{GSS}	Gate-Source Voltage - Continuous	20	V
I_D	Drain Current - Continuous (Note 1a)	0.51	A
	- Pulsed	1.5	
P_D	Maximum Power Dissipation (Note 1a)	0.96	W
	(Note 1b)	0.9	
	(Note 1c)	0.7	
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	130	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	60	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	50			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 40 V, V _{GS} = 0 V			1	μA
		T _J = 125 °C			500	
I _{GSSF}	Gate - Body Leakage, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate - Body Leakage, Reverse	V _{GS} = -20 V, V _{DS} = 0 V			-100	nA
ON CHARACTERISTICS (Note 2)						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	1	1.9	2.5	V
		T _J = 125 °C	0.8	1.5	2.2	
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 0.51 A		1	2	Ω
		T _J = 125 °C		1.7	3.5	
		V _{GS} = 4.5 V, I _D = 0.35 A		1.6	4	
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 10 V	1.5			A
g _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 0.51 A		400		mS
DYNAMIC CHARACTERISTICS						
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		20		pF
C _{oss}	Output Capacitance			13		pF
C _{rss}	Reverse Transfer Capacitance			5		pF
SWITCHING CHARACTERISTICS (Note 2)						
t _{D(on)}	Turn - On Delay Time	V _{DD} = 25 V, I _D = 0.25 A, V _{GS} = 10 V, R _{GEN} = 25 Ω		6	20	nS
t _r	Turn - On Rise Time			6	20	
t _{D(off)}	Turn - Off Delay Time			11	20	
t _f	Turn - Off Fall Time			5	20	
Q _g	Total Gate Charge	V _{DS} = 25 V, I _D = 0.51 A, V _{GS} = 10 V		1		nC
Q _{gs}	Gate-Source Charge			0.19		nC
Q _{gd}	Gate-Drain Charge			0.33		nC

ELECTRICAL CHARACTERISTICS (T_A = 25 °C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
DRAIN-SOURCE DIODE CHARACTERISTICS						
I _S	Maximum Continuous Source Current				0.51	A
I _{SM}	Maximum Pulse Source Current (Note 2)				1.5	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0.51 A (Note 2)		0.8	1.2	V

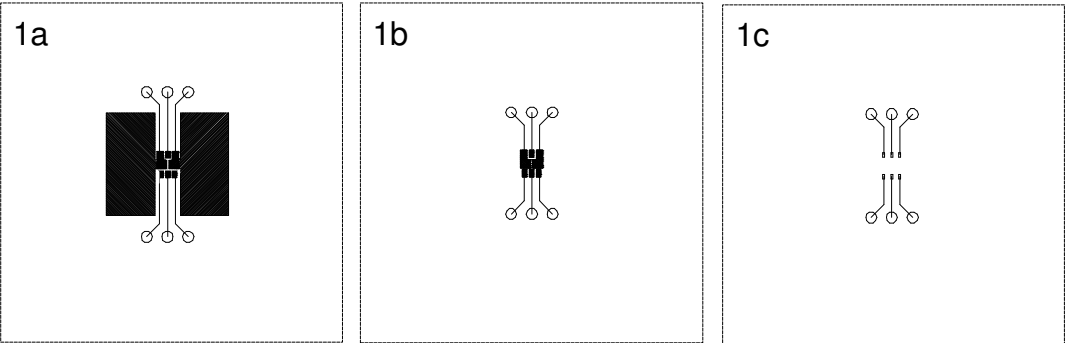
Notes:

1. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.

$$P_D(t) = \frac{T_J - T_A}{R_{\theta J A}(t)} = \frac{T_J - T_A}{R_{\theta J C} + R_{\theta C A}(t)} = I_D^2(t) \times R_{DS(ON)} @ T_J$$

Typical R_{θJA} for single device operation using the board layouts shown below on 4.5"x5" FR-4 PCB in a still air environment:

- a. 130°C/W when mounted on a 0.125 in² pad of 2oz copper.
- b. 140°C/W when mounted on a 0.005 in² pad of 2oz copper.
- c. 180°C/W when mounted on a 0.0015 in² pad of 2oz copper.



Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

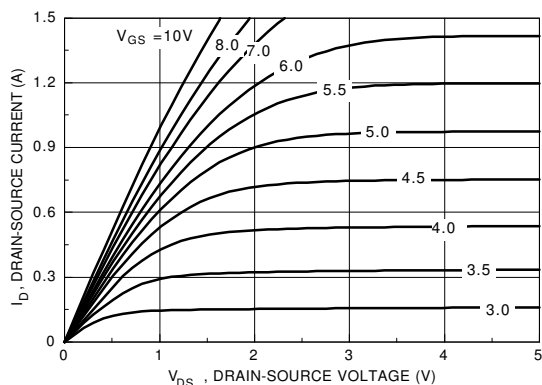


Figure 1. On-Region Characteristics.

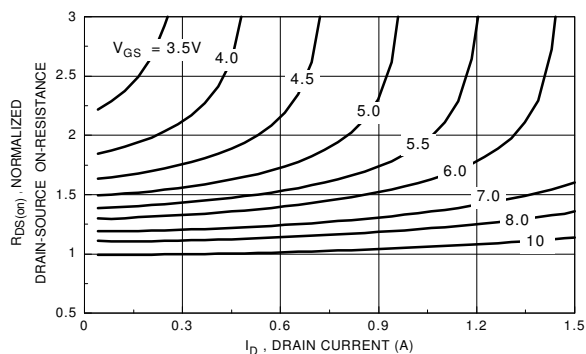


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

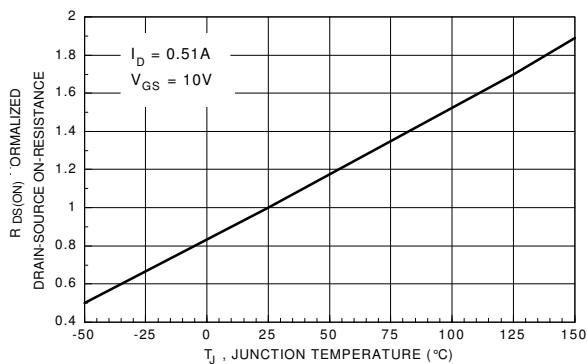


Figure 3. On-Resistance Variation with Temperature.

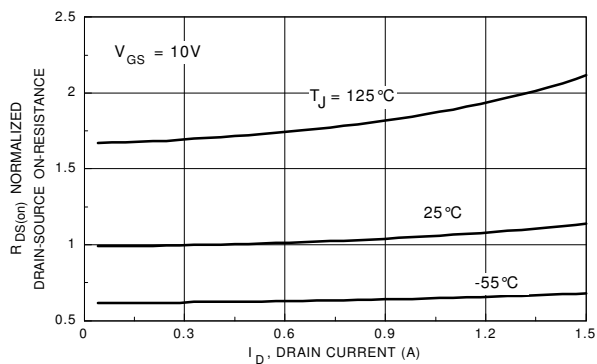


Figure 4. On-Resistance Variation with Drain Current and Temperature.

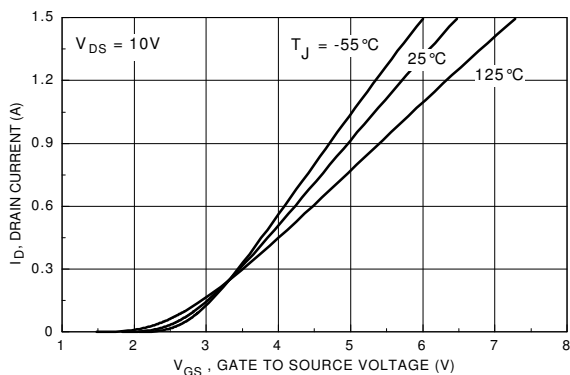


Figure 5. Transfer Characteristics.

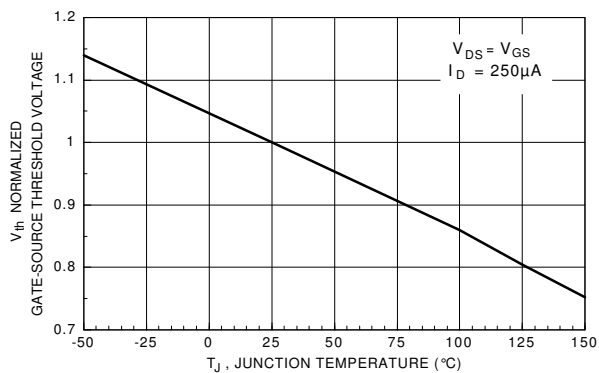


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

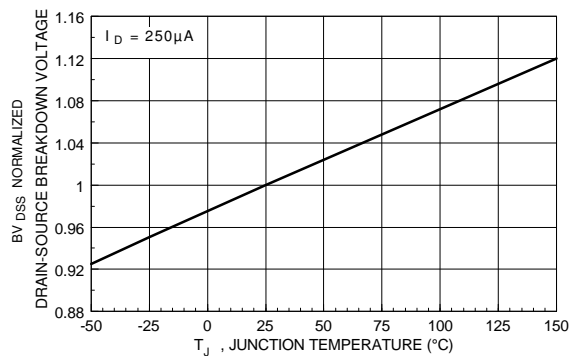


Figure 7. Breakdown Voltage Variation with Temperature.

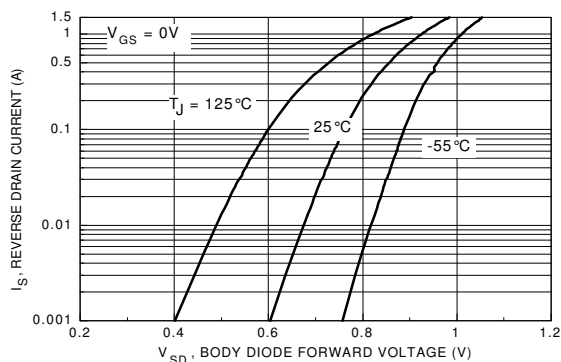


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.

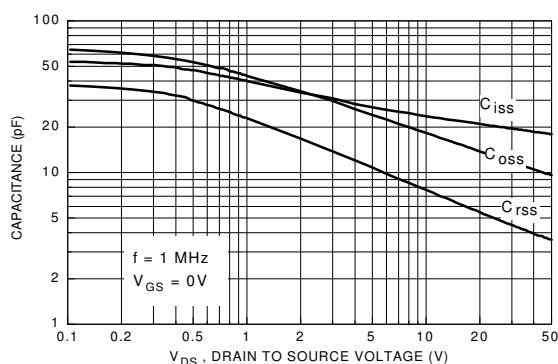


Figure 9. Capacitance Characteristics.

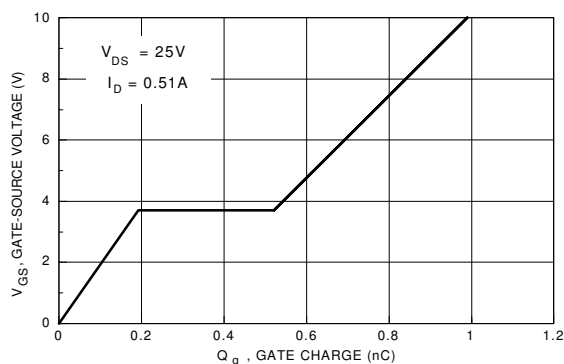


Figure 10. Gate Charge Characteristics.

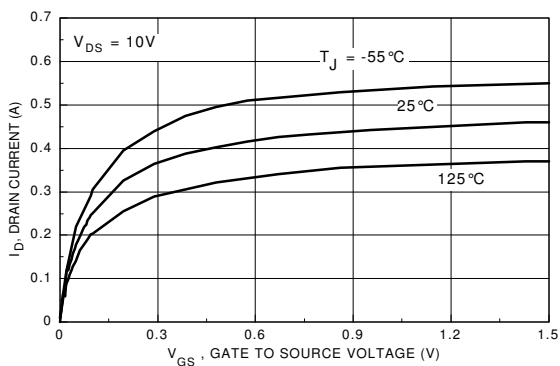


Figure 11. Transconductance Variation with Drain Current and Temperature.

Typical Thermal Characteristics

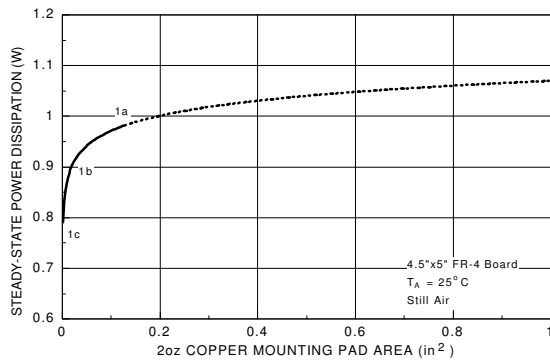


Figure 12. SOT-6 Dual Package Maximum Steady-State Power Dissipation versus Copper Mounting Pad Area.

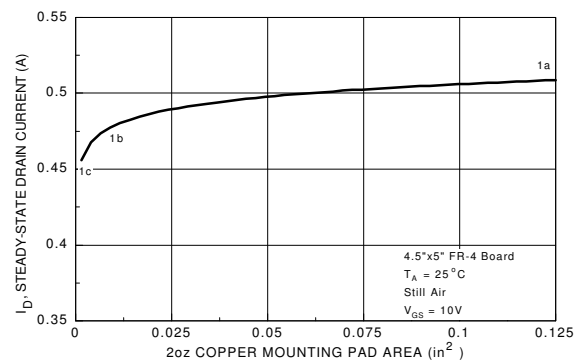


Figure 13. Maximum Steady-State Drain Current versus Copper Mounting Pad Area.

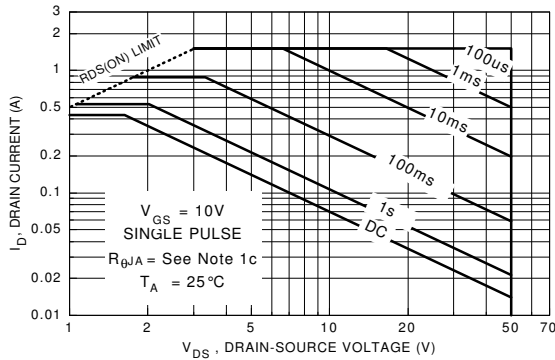


Figure 14. Maximum Safe Operating Area.

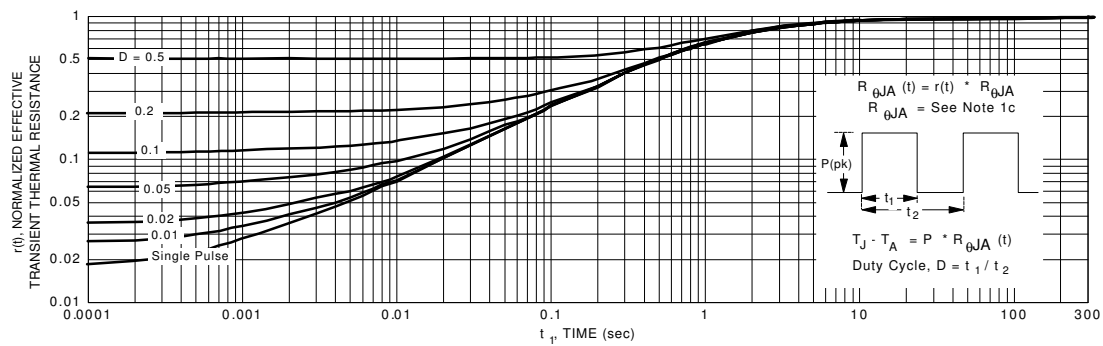


Figure 15. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1c. Transient thermal response will change depending on the circuit board design.

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